

# Linde Electronics List of Gases



	CLEANING	DEPOSITION	DOPING	ETCH	ANNEALING	LITHOGRAPHY	PURGING
Ar (Argon)							●
Ar/F <sub>2</sub> /Ne (Argon/Fluorine/Neon - ArF laser)						●	
Ar/Xe/Ne (Argon/Xenon/Neon - ArF laser)						●	
AsH <sub>3</sub> (Arsine)		●	●				
BF <sub>3</sub> (Boron trifluoride)			●				
<sup>11</sup> BF <sub>3</sub> (Boron-11 trifluoride)			●				
<sup>11</sup> B <sub>2</sub> H <sub>6</sub> (Enriched diborane)			●				
B <sub>2</sub> H <sub>6</sub> (Diborane)			●				
BCl <sub>3</sub> (Boron trichloride)				●			
C <sub>2</sub> F <sub>6</sub> (Hexafluoroethane) Halocarbon 116	●	●		●			
C <sub>2</sub> H <sub>2</sub> (Acetylene)		●					
C <sub>3</sub> F <sub>8</sub> (Octafluoropropane) Halocarbon 218				●			
C <sub>3</sub> H <sub>6</sub> (Propylene)		●					
C <sub>4</sub> F <sub>6</sub> (Hexafluoro-3-butadiene) Halocarbon 2316				●			
C <sub>4</sub> F <sub>8</sub> (Octafluorocyclobutane) Halocarbon 318				●			
C <sub>5</sub> F <sub>8</sub> (Octafluorocyclopentene) Halocarbon c1418				●			
CF <sub>4</sub> (Carbon tetrafluoride) Halocarbon 14	●			●			

Linde Electronics Gases

	CLEANING	DEPO-SITION	DOPING	ETCH	ANNEALING	LITHO-GRAPHY	PURGING
CH <sub>2</sub> F <sub>2</sub> (Difluoromethane) Halocarbon 32				●			
C <sub>2</sub> HF <sub>5</sub> (Pentafluoroethane)				●			
CH <sub>3</sub> F (Fluoromethane) Halocarbon 41				●			
CH <sub>4</sub> (Methane)		●		●			
CHF <sub>3</sub> (Trifluoromethane) Halocarbon 23				●			
Cl <sub>2</sub> (Chlorine)	●			●			
ClF <sub>3</sub> (Chlorine trifluoride)	●						
CO (Carbon monoxide)		●		●			
CO <sub>2</sub> (Carbon dioxide)				●		●	
COS (Carbonyl sulfide)		●					
D <sub>2</sub> (Deuterium)					●		
DEZ (Diethylzinc)		●	●				
F <sub>2</sub> (Fluorine)	●						
F <sub>2</sub> /N <sub>2</sub> (Fluorine/Nitrogen)	●						
GeCl <sub>4</sub> (Germanium tetrachloride)		●					
GeH <sub>4</sub> (Germane)		●	●				
He (Helium)							●
H <sub>2</sub> (Hydrogen)					●	●	●
H <sub>2</sub> S (Hydrogen sulfide)		●					

Linde Electronics Gases

	CLEANING	DEPOSITION	DOPING	ETCH	ANNEALING	LITHOGRAPHY	PURGING
H <sub>2</sub> Se (Hydrogen selenide)	●						
HBr (Hydrogen bromide)				●			
HCDS (Hexachlorodisilane)		●					
HCl (Hydrogen chloride)		●		●			
HF (Hydrogen fluoride)				●			
Kr (Krypton)				●		●	
Kr/F <sub>2</sub> /Ne (Krypton/Fluorine/Neon - KrF laser)						●	
Kr/Ne (Krypton/Neon - KrF laser)						●	
N <sub>2</sub> (Nitrogen)							●
N <sub>2</sub> O (Nitrous oxide)		●		●			
ND <sub>3</sub> (Deuterated ammonia)		●					
Ne (Neon)						●	
Ne/HCl/H <sub>2</sub> mixture (Neon/Hydrogen chloride/Hydrogen)						●	
NF <sub>3</sub> (Nitrogen trifluoride)	●			●			
NH <sub>3</sub> (Ammonia)		●					
NO (Nitric oxide)		●		●			
O <sub>2</sub> (Oxygen)	●	●		●			
PH <sub>3</sub> (Phosphine)		●	●				

Linde Electronics Gases

	CLEANING	DEPOSITION	DOPING	ETCH	ANNEALING	LITHOGRAPHY	PURGING
SF <sub>6</sub> (Sulfur hexafluoride)	●			●			
Si <sub>2</sub> Cl <sub>6</sub> (HCDS - Hexachlorodisilane)		●					
Si <sub>2</sub> H <sub>6</sub> (Disilane)		●					
SiCl <sub>4</sub> (Tetrachlorosilane - silicon tetrachloride)		●					
SiD <sub>4</sub> (Deuterated silane)		●					
SiF <sub>4</sub> (Tetrafluorosilane - also know as silicon tetrafluoride)		●		●			
SiH <sub>2</sub> Cl <sub>2</sub> (Dichlorosilane)		●					
SiH <sub>4</sub> (Silane)		●					
SiHCl <sub>3</sub> (TCS - Trichlorosilane)		●					
SO <sub>2</sub> (Sulfur dioxide)		●					
TEA (Triethylaluminum)		●					
TMA (Trimethylaluminum)		●					
TMB (Trimethylboron)			●				
TMS (3MS - Trimethylsilane)		●					
WF <sub>6</sub> (Tungsten hexafluoride)		●					
Xe (Xenon)				●		●	
XeF <sub>2</sub> (Xenon difluoride)				●			
Mixtures (calibration, etc.)							

[www.linde.com/electronics](http://www.linde.com/electronics)

For more information, please contact us at [electronicsinfo@linde.com](mailto:electronicsinfo@linde.com).